

CLAIMS

We claim:

1. A method for fabricating an electrical circuit, comprising the steps of:
depositing a layer of a first conductive material onto a surface of a substrate;
depositing a layer of a second conductive material onto said layer of a first conductive material;
selectively etching a portion of said layer of a second conductive material; and
selectively etching a portion of said layer of a first conductive material.
2. The method of claim 1 wherein said layer of first conductive material is substantially transparent.
3. The method of claim 1 wherein said first conductive material is indium tin oxide.
4. The method of claim 1 wherein said second conductive material is copper.
5. The method of claim 4 further comprising the step of electrically connecting an electrical component to said second conductive material.
6. The method of claim 5 wherein said step of electrically connecting said electrical component to said second conductive material comprises soldering said electrical component to said second conductive material.

7. The method of claim 1 further comprising the step of depositing a layer of a third conductive material onto said layer of second conductive material.
8. The method of claim 7 wherein said layer of second conductive material is substantially transparent.
9. The method of claim 7 wherein said second conductive material is an oxide of niobium.
10. The method of claim 7 wherein said third material is copper.
11. The method of claim 7 further comprising the step of electrically connecting an electrical component to said second conductive material.
12. The method of claim 11 wherein said step of electrically connecting said electrical component to said second conductive material comprises soldering said electrical component to said second conductive material.
13. The method of claim 1 wherein at least one of said steps of depositing occur in a substantial vacuum.
14. The method of claim 1 further comprising the step of pretreating said surface of said substrate to enhance adhesion of said layer of first conductive material to said substrate.

15. A method for fabricating an electrical circuit, comprising the steps of:
depositing a layer of a first conductive material onto a surface of a substrate;
depositing a layer of a second conductive material onto said layer of a first conductive material;
selectively etching a first portion of said layer of a second conductive material and a portion of said layer of first conductive material; and
selectively etching a second portion of said layer of a second conductive material.
16. The method of claim 15 wherein said portion of said layer of first conductive material substantially corresponds to said first portion of said layer of a second conductive material.
17. The method of claim 15 further comprising the steps of:
depositing a layer of a third conductive material onto said layer of a second conductive material; and
selectively etching a first portion of said layer of a third conductive material.
18. The method of claim 15 wherein said portion of said layer of third conductive material substantially corresponds to said portion of said layer of said first conductive material and said first portion of said layer of a second conductive material.
19. A method for fabricating an electrical circuit, comprising the steps of:
depositing a layer of a first conductive material onto a first surface of a substrate;

depositing a layer of a second conductive material onto a second surface of said substrate;

selectively etching a portion of said layer of a first conductive material;

selectively etching a portion of said layer of a second conductive material;

perforating said substrate at a predetermined location; and

electrically coupling said layer of a first conductive material with said layer of a second conductive material.

20. An electrical circuit platform having transparent and conventional circuit portions, comprising:

a substrate, at least a portion of which is transparent;

a layer of a first conductive material disposed on said substrate in a first predetermined pattern; and

a layer of second conductive material disposed on said first conductive material in a second predetermined pattern.

21. The electrical circuit platform of claim 20 wherein said layer of first conductive material is substantially transparent.

22. The electrical circuit platform of claim 20 wherein said second conductive material is a conventional conductive material.

23. The electrical circuit platform of claim 20, further comprising a layer of a third

conductive material disposed on said second conductive material in a third predetermined pattern.

24. The electrical circuit platform of claim 23 wherein said layer of second conductive material is substantially transparent.

25. The electrical circuit platform of claim 24 wherein said third conductive material is a conventional conductive material.